

Bias Resistor Transistor

PNP Silicon Surface Mount Transistor with Monolithic Bias Resistor Network

• Applications

Inverter, Interface, Driver

Features

- Built-in bias resistors enable the configuration of an inverter circuit without connecting external input resistors (see equivalent circuit).
- 2) The bias resistors consist of thin-film resistors with complete isolation to allow positive biasing of the input. They also have the advantage of almost completely eliminating parasitic effects.
- 3) Only the on/off conditions need to be set for operation, making the device design easy.
- We declare that the material of product compliance with RoHS requirements.

● Absolute maximum ratings (Ta=25°C)

Parameter	Symbol	Limits	Unit	
Supply voltage	Vcc	-50	V	
Input voltage	Vin	−10 to +5	V	
Output current	lo	-100	mA	
	IC(Max.)	– 100		
Power dissipation	Po	200	mW	
Junction temperature	Tj	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

DEVICE MARKING AND RESISTOR VALUES

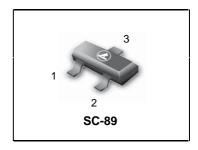
Device	vice Marking		R2 (K)	Shipping	
LDTA113ZET1G	E8	1	10	3000/Tape & Reel	
LDTA113ZET3G	E8	1	10	10000/Tape & Reel	

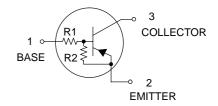
●Electrical characteristics (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Innut voltore	VI(off)	_	_	-0.3	.,	Vcc=-5V, Io=-100 μA
Input voltage	VI(on)	-3	_	_	V	Vo=-0.3V, Io=-20mA
Output voltage	VO(on)	_	_	-0.3	٧	Io/I=-10mA/-0.5mA
Input current	lı	_	_	-7.2	mA	V=-5V
Output current	IO(off)	_	_	-0.5	μΑ	Vcc=-50V, Vi=0V
DC current gain	Gı	33	_	_	_	Vo=-5V,lo=-5mA
Input resistance	R ₁	0.7	1	1.3	kΩ	_
Resistance ratio	R2/R1	8	10	12	_	_
Transition frequency	fτ	_	250	_	MHz	VcE=-10V, IE=5mA, f=100MHz *

^{*} Transition frequency of the device

LDTA113ZET1G







LDTA113ZET1G

•Electrical characteristic curves

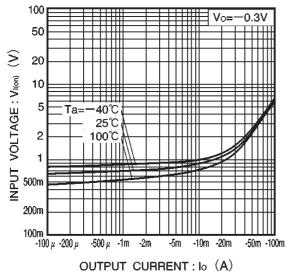


Fig.1 Input voltage vs. output current (ON characteristics)

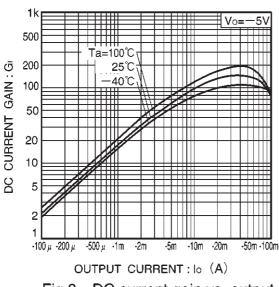


Fig.3 DC current gain vs. output current

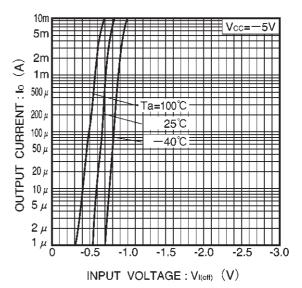


Fig.2 Output current vs. input voltage (OFF characteristics)

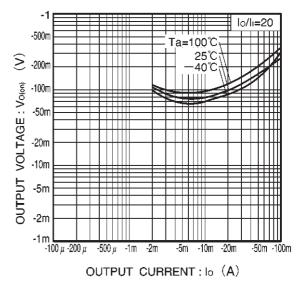
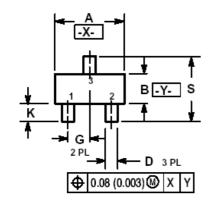


Fig.4 Output voltage vs. output current



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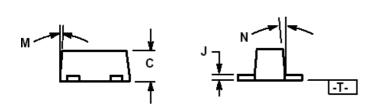


NOTES:

1.DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

2.CONTROLLING DIMENSION: MILLIMETERS
3.MAXIMUM LEAD THICKNESS INCLUDES LEAD
FINISH THICKNESS. MINIMUM LEAD THICKNESS
IS THE MINIMUM THICKNESS OF BASE
MATERIAL.

4.463C-01 OBSOLETE, NEW STANDARD 463C-02.



	MI	LLIMETE	RS	INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	1.50	1.60	1.70	0.059	0.063	0.067	
В	0.75	0.85	0.95	0.030	0.034	0.040	
С	0.60	0.70	0.80	0.024	0.028	0.031	
D	0.23	0.28	0.33	0.009	0.011	0.013	
G	0.50 BSC			0.020 BSC			
Н	0.53 REF			0.021 REF			
J	0.10	0.15	0.20	0.004	0.006	0.008	
K	0.30	0.40	0.50	0.012	0.016	0.020	
L	1.10 REF			0.043 REF			
M			10 °	-		10°	
N			10 °			10°	
S	1.50	1.60	1.70	0.059	0.063	0.067	

